

Customer Notification of Product/Process Changes

Page: 1/2

*PCN No.: PCN-0114

*Subject: Planar wafer IR improvement

*Issued Date: Oct/05/2018

*Effective date: Dec/05/2018

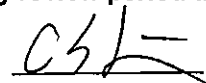
*Affected category: APD/SMD/TO-220/ITO-220

*Affected Family: see attached file

Change Item	<input type="checkbox"/> Material <input type="checkbox"/> Design <input type="checkbox"/> Process <input checked="" type="checkbox"/> Others
Impact Item	1. Product P/N : <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No 3. Label : <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No 2. Marking : <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No 4. Other items : <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No
Other Related Item	NA
Change Purpose	IR improvement
Description of Change	Wafer passivation optimization
Related Report	<input checked="" type="checkbox"/> Electrical Test Report (as the attachment) <input type="checkbox"/> SGS / MCD_MDS Report <input type="checkbox"/> ESD Report (as the attachment) <input type="checkbox"/> Mechanical Test Report <input checked="" type="checkbox"/> Others(ex. Impacted part list) (as the attachment)
Sample availability	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
Customer Approval	<input type="checkbox"/> Approve <input type="checkbox"/> Disapprove
Customer Requirement (ex. Last Buy requirement)	

(Note):

- 1.If you need sample(s) or any question, please contact with our Salesperson within 30day
- 2.LSC will follow WW industry standard spec (JESD46D) criteria define as below.
 - A. Customers should acknowledge receipt of the PCN within 30 day period constitutes
 - B. Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.
 - C. After acknowledgement, lack of additional response within the 90 day period constitutes acceptance of the change.
 - D. If customer requires additional time to perform samples testing, beyond the 90 day review period an extension must be negotiate
Quality Assurance



Attachments:

1. Part list of wafer passivation optimization
2. Wafer passivation optimization structure
3. IR (Reliability) distribution comparison
4. IR (Normal testing) distribution comparison
5. Reliability test summary